

Abstract

Disclosed is a cover for use in transporting an electrical header which comprises a dielectric housing, terminals mounted on the housing and pins arranged in an array comprising at least two generally parallel longitudinal rows of pins. The cover comprises an upper section including a top surface, an outer and preferably an inner generally concentric wall member extend downwardly in spaced relation from the top section. A concentric groove is formed between said wall members and said wall members and the groove is positioned so that at least one pin in each of said row of pins is engageable in said groove. A recess may also be positioned in the center of the upper surface to increase pick up efficiency. A method for using the cover to manipulate electrical headers is also disclosed.

This Sheet Has Been Replaced
